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To the Director, U.S. Patent and

ached original documents or copy thereof.

	[3
1. Name of conveying parties: (List using letters or numbers for multiple parties) A. Lior Kogut B. Ming-Hau Tung C. Brian Arbuckle Additional names of conveying parties attached? () Yes (X) No 3. Nature of conveyance: (X) Assignment () Security Agreement () Merger () Change of Name	2. Name and address of receiving party: Name: Qualcomm MEMS Technologies, Inc. Internal Address: Street Address: 5775 Morehouse Drive City: San Diego State: CA ZIP: 92121 Additional names of receiving parties attached? () Yes (X) No
() Other: Execution Date: (List as in section 1 if multiple signatures) A. June 27, 2006 B. June 27, 2006 C. June 27, 2006	4. US or PCT Application number(s) or US Patent number(s): (X) Application(s) filed herewith Additional numbers attached? () Yes (X) No
 5. Party to whom correspondence concerning document should be mailed: Customer No. 59,747 Address: Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14th Floor Irvine, CA 92614 Return Fax: (949) 760-9502 Attorney's Docket No.: QCO.072A2 	Total number of applications and patents involved: 1
7. Total fee (37 CFR 1.21(h)): \$40.00 (X) Enclosed	8. Deposit account number: 11-1410 Please charge this account for any additional fees which may be required, or credit any overpayment to this account.
9. Statement and signature. To the best of my knowledge and belief, the foregoing is a true copy of the original document. Bruce S. Itchkawitz Name of Person Signing 47,677 Registration No.	g information is true and correct, and any attached copy
Total number of pages including cover	sheet attachments and document: 3

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Application No.: Unknown Client Code: QCO.072A2 / Qualcomm #060310U2 Filing Date: Herewith Page 1

ASSIGNMENT

WHEREAS, Lior Kogut, an Israeli citizen, residing at 920 Rockefeller Drive, Apartment 9A, Sunnyv	ale,
California 94087, Ming-Hau Tung, a United States citizen, residing at 1712 48th Avenue, San Francisco, CA 94122	and
Brian Arbuckle, a United States citizen, residing at 563 Everett Drive, Danville, California 94526 (collectively Assigno	rs),
have invented certain new and useful improvements in a SUPPORT STRUCTURE FOR FREE-STANDING ME	MS
DEVICE AND METHODS FOR FORMING THE SAME for which we caused to be filed an application for Letters Pa	ent
in the United States; and we hereby authorize and request the attorneys of Knobbe, Martens, Olson & Bear, LLP, Custor	ner
No. 20,995, to insert here in parentheses (Application Number, filed, 2006), the application Number, filed	ion
number of said application when known;	

AND WHEREAS, QUALCOMM MEMS Technologies, Inc. (hereinafter "ASSIGNEE"), a Delaware corporation, with its principal place of business at 5775 Morehouse Drive, San Diego, California 92121, U.S.A, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional application(s) to which said Application claims, or is entitled to claim, priority, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I DO HEREBY sell, assign, transfer, and convey to the said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to the said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 27 day of April, 2006. Lior Komit

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 27 day of April, 2006.

Ming-Hau Tung

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IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 27 day of April, 2006.

Brian Arbuckle

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS Technologies, Inc. this ____ day of April, 2006.

QUALCOMM MEMS Technologies, Inc.

Name:
Title:

Application No.: Unknown

Filing Date: Herewith

062206

PATENT
RECORDED: 06/28/2006 REEL: 018023 FRAME: 0344